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Docket No. 740756-2712
Application No. 10/772,419
Page 2**IN THE CLAIMS:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently amended) A manufacturing method of a display device comprising:
forming a conductive film over a substrate by ejecting liquid droplets containing conductive particles by using a first liquid droplet ejecting apparatus comprising a liquid droplet ejecting head provided with a plurality of liquid droplet ejecting nozzles arranged linearly;
forming a resist pattern ~~is~~ locally on the conductive film by using a second liquid droplet ejecting apparatus comprising a liquid droplet ejecting head provided with a plurality of liquid droplet ejecting nozzles arranged linearly; ~~and~~
forming a wiring by etching the conductive film with the resist pattern as a mask at an atmospheric pressure or a pressure close to the atmospheric pressure by using a first plasma generating device ~~plasma-generating-device means comprising one pair of electrodes. a plurality of pairs of electrodes;~~
forming an insulating film over the wiring; and
forming a contact hole by etching the insulating film at the atmospheric pressure or a pressure close to the atmospheric pressure by using a second plasma generating device provided with a pair of electrodes.
2. (Canceled)
3. (Currently Amended) A manufacturing method of a display device according to claim 1,
wherein after forming the wiring, the resist film is locally etched at an atmospheric pressure or a pressure close to the atmospheric pressure by using ~~the plasma-generating means provided with one pair of electrodes. the second plasma generating device.~~
4. (Currently amended) A manufacturing method of a display device comprising:
forming a conductive film over a substrate by ejecting liquid droplets containing

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conductive particles by using a liquid droplet ejecting apparatus comprising a liquid droplet ejecting head provided with a plurality of liquid droplet ejecting nozzles arranged linearly; and

after forming the conductive film, forming a wiring by etching an unnecessary portion of the conductive film locally at an atmospheric pressure or a pressure close to the atmospheric pressure by using a ~~plasma generating means provided with one pair of electrodes at an atmospheric pressure or a pressure close to the atmospheric pressure.~~ first plasma generating device comprising a plurality of pairs of electrodes;

forming an insulating film over the wiring; and

forming a contact hole by etching the insulating film at the atmospheric pressure or a pressure close to the atmospheric pressure by using a second plasma generating device provided with a pair of electrodes.

5. (Currently amended) A manufacturing method of a display device comprising:

forming a conductive film ~~on~~ over a substrate by using a liquid droplet ejecting apparatus comprising a liquid droplet ejecting head provided with a plurality of liquid droplet ejecting nozzles arranged linearly; and

forming a resist pattern on the conductive film;

after forming the resist pattern, forming a wiring by etching an unnecessary portion of the conductive film locally at an atmospheric pressure or a pressure close to the atmospheric pressure by using a ~~plasma generating means provided with one pair of electrodes at an atmospheric pressure or a pressure close to the atmospheric pressure.~~ second plasma generating device comprising a plurality of pairs of electrodes;

forming an insulating film over the wiring; and

forming a contact hole by etching the insulating film at the atmospheric pressure or a pressure close to the atmospheric pressure by using a second plasma generating device provided with a pair of electrodes.

6. (Previously Presented) A manufacturing method of a display device according to claim 1, wherein the wiring includes at least one conductive material selected from the group consisting of Ag, Au, Cu, Ni, Pt, Pd, Ir, Rh, W, and Al, metal sulfide of Cd and Zn, oxide of

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Fe, Ti, Si, Ge, Si, Zr, Ba, and the like, and fine particles or dispersible nanoparticles of silver halide.

7. (Previously Presented) A manufacturing method of a display device according to claim 4, wherein the wiring includes at least one conductive material selected from the group consisting of Ag, Au, Cu, Ni, Pt, Pd, Ir, Rh, W, and Al, metal sulfide of Cd and Zn, oxide of Fe, Ti, Si, Ge, Si, Zr, Ba, and the like, and fine particles or dispersible nanoparticles of silver halide.

8. (Previously Presented) A manufacturing method of a display device according to claim 5, wherein the wiring includes at least one conductive material selected from the group consisting of Ag, Au, Cu, Ni, Pt, Pd, Ir, Rh, W, and Al, metal sulfide of Cd and Zn, oxide of Fe, Ti, Si, Ge, Si, Zr, Ba, and the like, and fine particles or dispersible nanoparticles of silver halide.

9. (Currently Amended) A manufacturing method of a display device according to claim 5, wherein after forming the wiring, the resist film is etched at an atmospheric pressure or a pressure close to the atmospheric pressure by using ~~the plasma generating means provided with one pair of electrodes.~~ the second plasma generating device.

10. (Previously Presented) A manufacturing method of a display device according to claim 1, wherein the one pair of electrodes are cylindrical electrodes.

11. (Previously Presented) A manufacturing method of a display device according to claim 4, wherein the one pair of electrodes are cylindrical electrodes.

12. (Previously Presented) A manufacturing method of a display device according to claim 5, wherein the one pair of electrodes are cylindrical electrodes.

13. (New) A manufacturing method of a display device according to claim 1, wherein after forming the wiring, the resist film is locally etched at an atmospheric

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pressure or a pressure close to the atmospheric pressure by using the first plasma generating device.

14. (New) A manufacturing method of a display device according to claim 5, wherein after forming the wiring, the resist film is etched at an atmospheric pressure or a pressure close to the atmospheric pressure by using the first plasma generating device.

15. (New) The manufacturing method of a display device according to claim 1, wherein the plurality of pairs of electrodes are arranged linearly.

16. (New) The manufacturing method of a display device according to claim 4, wherein the plurality of pairs of electrodes are arranged linearly.

17. (New) The manufacturing method of a display device according to claim 5, wherein the plurality of pairs of electrodes are arranged linearly.

18. (New) The manufacturing method of a display device according to claim 1, wherein the insulating film comprising at least one selected from the group consisting of a silicon nitride, a silicon oxide and an organic resin.

19. (New) The manufacturing method of a display device according to claim 4, wherein the insulating film comprising at least one selected from the group consisting of a silicon nitride, a silicon oxide and an organic resin.

20. (New) The manufacturing method of a display device according to claim 5, wherein the insulating film comprising at least one selected from the group consisting of a silicon nitride, a silicon oxide and an organic resin.

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